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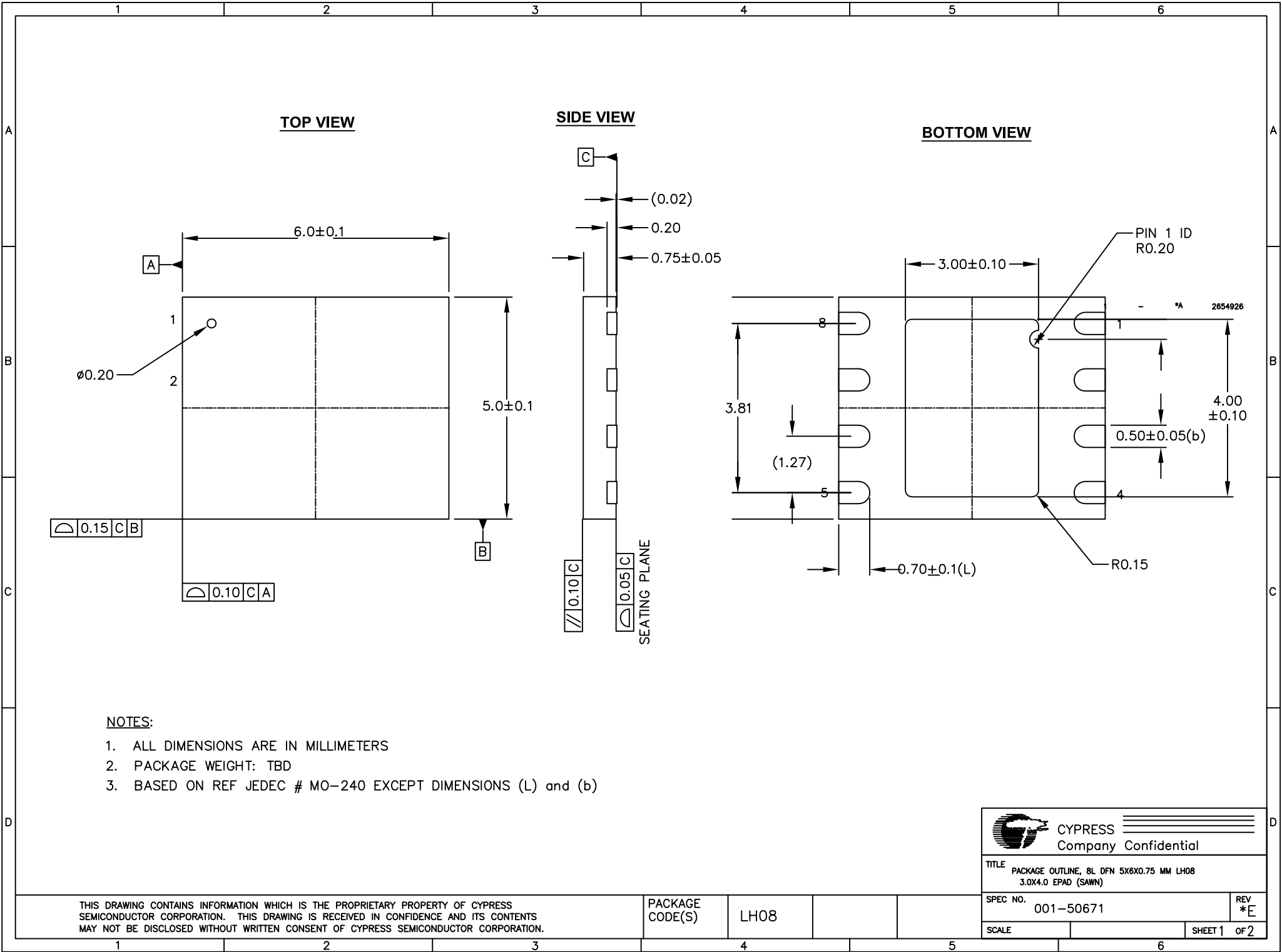
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

**Continuity of document content**

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.


**Continuity of ordering part numbers**

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.






NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS
- 2. PACKAGE WEIGHT: TBD
- 3. BASED ON REF JEDEC # MO-240 EXCEPT DIMENSIONS (L) and (b)

 CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 8L DFN 5X6X0.75 MM LH08 3.0X4.0 EPAD (SAWN)	
SPEC NO. 001-50671	REV *E
SCALE	SHEET 1 OF 2

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

PACKAGE CODE(S) LH08

1	2	3	4	5	6																												
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